

ABSTRACT

The present invention provides the colloidal silica slurry which does not have a bad influence, such as corrosion, to a silicon wafer and wiring material on a silicon wafer and inhibits growth of microbes, and whereof preserving stability is high because stability of particle diameters of a colloidal particle is superior and using for a long period continuously is possible. For providing the above, the colloidal silica slurry wherein hydrogen peroxide from 5 to 100 ppm is added.